

High Current FET Driver

FEATURES

- Totem Pole Output with 6A Source/Sink Drive
- 3ns Delay
- 20ns Rise and Fall Time into 2.2nF
- 8ns Rise and Fall Time into 30nF
- 4.7V to 18V Operation
- Inverting and Non-Inverting Outputs
- Under-Voltage Lockout with Hysteresis
- Thermal Shutdown Protection
- MINIDIP and Power Packages

DESCRIPTION

The UC1710 family of FET drivers is made with a high-speed Schottky process to interface between low-level control functions and very high-power switching devices-particularly power MOSFET's. These devices accept low-current digital inputs to activate a high-current, totem pole output which can source or sink a minimum of 6A.

Supply voltages for both V_{IN} and V_{C} can independently range from 4.7V to 18V. These devices also feature under-voltage lockout with hysteresis.

The UC1710 is packaged in an 8-pin hermetically sealed dual in-line package for -55°C to +125°C operation. The UC2710 and UC3710 are specified for a temperature range of -40°C to +85°C and 0°C to +70°C respectively and are available in either an 8-pin plastic dual in-line or a 5-pin, TO-220 package. Surface mount devices are also available.

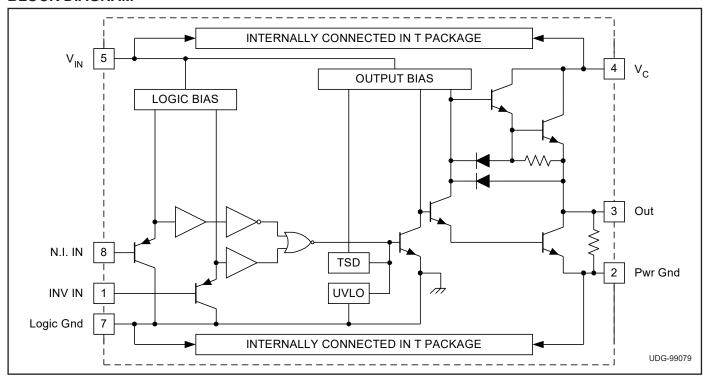
ORDERING INFORMATION

	TEMPERATURE RANGE	PACKAGE
UC1710J	–55°C to +125°C	8 pin CDIP
UC2710DW	–40°C to +85°C	Not Available
UC2710J		Not Available
UC2710N		8 pin PDIP
UC2710T		5 pin TO220
UC3710DW	0°C to +70°C	16 pin SOIC-wide
UC3710N		8 pin PDIP
UC3710T		5 pin TO220

TRUTH TABLE

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BLOCK DIAGRAM



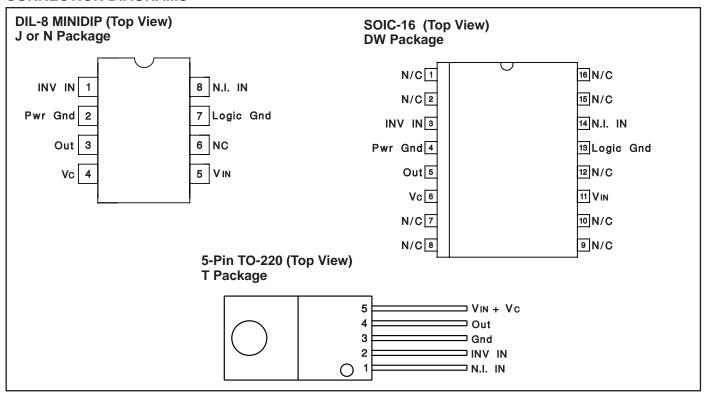
ABSOLUTE MAXIMUM RATINGS

	N-Package	J-Package	T-Package
Supply Voltage, Vin	20V	20V	20V
Collector Supply Voltage, V _C	20V	20V	20V
Operating Voltage	18V		18V
Output Current (Source or Sink)			
Steady-State	± 500mA	± 500mA	± 1A
Digital Inputs	–0.3V-VIN	0.3V - V _{IN}	0.3V - VIN
Power Dissipation at Ta=25°C	1W	1W	3W
Power Dissipation at T (Case) = 25°C	2W	2W	25W
Operating Junction Temperature5	55°C to +150°C	. –55°C to +150°C	-55°C to +150°C
Storage Temperature6	5°C to +150°C	. –65°C to +150°C	-65°C to +150°C
Lead Temperature (Soldering, 10 seconds)	300°C	300°C	300°C
Operating Voltage Output Current (Source or Sink) Steady-State Digital Inputs Power Dissipation at Ta=25°C Power Dissipation at T (Case) = 25°C Operating Junction Temperature Storage Temperature -6	± 500mA0.3V-VIN 1W 2W 5°C to +150°C	±500mA 0.3V - V _{IN} 1W 2W 55°C to +150°C 65°C to +150°C	

Note 1: All currents are positive into, negative out of the specified terminal.

Note 2: Consult Unitrode Integrated Circuits databook for information regarding thermal specifications and limitations of packages.

CONNECTION DIAGRAMS



ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $V_{IN} = V_C = 15V$, No load, $T_A = T_{.I}$

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
V _{IN} Supply Current	V_{IN} =18V, V_{C} =18V, Output Low		26	35	mA
	V _{IN} =18V, V _C =18V, Output High		21	30	mA
V _C Supply Current	V _{IN} =18V, V _C =18V, Output Low		1.5	5.0	mA
	V _{IN} =18V, V _C =18V,Output High		5.0	8	mA
UVLO Threshold	V _{IN} High to Low	3.8	4.1	4.4	V
	V _{IN} Low to High	4.1	4.4	4.8	V

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $V_{IN} = V_C = 15V$, No load,

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
UVLO Threshold Hysteresis		0.1	0.3	0.5	V
Digital Input Low Level				0.8	V
Digital Input High Level		2.0			V
Digital Input Current	Digital Input = 0.0V	-70	-4.0		μΑ
Output High Sat., V _C – V _O	I _O = -100mA		1.35	2.2	V
	I _O = -6A		3.2	4.5	V
Output Low Sat., Vo	I _O = 100mA		0.25	0.6	V
	I _O = 6A		3.4	4.5	V
Thermal Shutdown			165		°C
From Inv., Input to Output (Note 3, 4):					
Rise Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	70	ns
10% to 90% Rise	CL = 0		20	40	ns
	CL = 2.2nF		25	40	ns
	CL = 30nF		85	150	ns
Fall Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	80	ns
90% to 10% Fall	CL = 0		15	40	ns
	CL = 2.2nF		20	40	ns
	CL = 30nF		85	150	ns
From N.I. Input to Output (Note 3,4):					
Rise Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	70	ns
10% to 90% Rise	CL = 0		20	40	ns
	CL = 2.2nF		25	40	ns
	CL = 30nF		85	150	ns
Fall Time Delay	CL = 0		35	70	ns
	CL = 2.2nF		35	70	ns
	CL = 30nF		35	80	ns
90% to 10% Fall	CL = 0		15	40	ns
	CL = 2.2nF		20	50	ns
	CL = 30nF		85	150	ns
Total Supply Current at 200kHz Input Switching Frequency	T _A = 25°C (Note 5) CL = 0		30	40	mA

Note: 3. Delay measured from 50% input change to 10% output change.

Note: 4. Those parameters with CL = 30nF are not tested in production.

Note: 5. Inv. Input pulsed at 50% duty cycle with N.I. Input = 3V. or N.I. Input pulsed at 50% duty cycle with Inv. Input = 0V.





8-Apr-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-0152001QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	0152001QPA UC1710	Samples
5962-0152001VPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	0152001VPA UC1710	Samples
UC1710J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UC1710J	Samples
UC1710J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	0152001QPA UC1710	Samples
UC2710N	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UC2710N	Samples
UC2710NG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UC2710N	Samples
UC2710T	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	UC2710T	Samples
UC2710TG3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	UC2710T	Samples
UC3710DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3710DW	Samples
UC3710DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3710DW	Samples
UC3710N	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU Call TI	N / A for Pkg Type	0 to 70	UC3710N	Samples
UC3710NG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	Call TI	N / A for Pkg Type	0 to 70	UC3710N	Samples
UC3710T	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	0 to 70	UC3710T	Samples
UC3710TG3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	0 to 70	UC3710T	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

PACKAGE OPTION ADDENDUM



8-Apr-2018

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF UC1710, UC1710-SP, UC3710:

Catalog: UC3710, UC1710

Military: UC1710

Space: UC1710-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



PACKAGE OPTION ADDENDUM

8-Apr-2018

• Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
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UC1710J	ACTIVE	CDIP	JG	8	50	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	UC1710J	Samples
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UC3710N	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	UC3710N	Samples
UC3710NG4	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	UC3710N	Samples
UC3710T	ACTIVE	TO-220	KC	5	50	RoHS & Green	SN	N / A for Pkg Type	0 to 70	UC3710T	Samples
UC3710TG3	ACTIVE	TO-220	KC	5	50	RoHS & Green	SN	N / A for Pkg Type	0 to 70	UC3710T	Samples

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PACKAGE OPTION ADDENDUM

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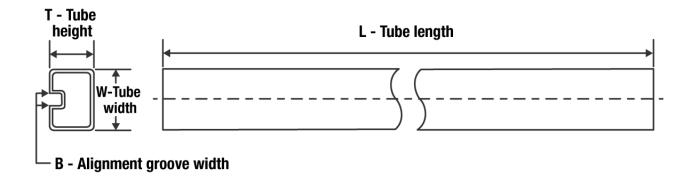
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Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application



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TUBE



*All dimensions are nominal

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Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
UC2710N	Р	PDIP	8	50	506	13.97	11230	4.32
UC3710DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC3710DWG4	DW	SOIC	16	40	507	12.83	5080	6.6
UC3710N	Р	PDIP	8	50	506	13.97	11230	4.32
UC3710NG4	Р	PDIP	8	50	506	13.97	11230	4.32
UC3710T	KC	TO-220	5	50	546	31	11930	3.17
UC3710TG3	KC	TO-220	5	50	546	31	11930	3.17

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